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# Single-input Voltage, 30A Buck Regulators with PVID

# OPTIMOS IPOL IR38265

## FEATURES

- Internal LDO allows single 16V operation
- Output Voltage Range: 0.5V to 0.875*PVin
- 0.5% accurate Reference Voltage
- Enhanced line/load regulation with Feedforward
- Frequency programmable by I2C up to 1.5 MHz
- Enable input with Voltage Monitoring Capability
- Remote Sense Amplifier with True Differential Voltage Sensing
- 3 pins (PVID) to program output voltage
- Fast mode I2C interface for programming, sequencing and margining output voltage, and for monitoring input voltage, output voltage, output current and temperature.
- I2C configurable fault thresholds for input UVLO, output OVP, OCP and thermal shutdown.
- Thermally compensated pulse-by-pulse current limit and Hiccup Mode Over Current Protection
- Dedicated output voltage sensing for power good indication and overvoltage protection which remains active even when Enable is low.
- Enhanced Pre-Bias Start up
- Integrated MOSFET drivers and Bootstrap diode
- Operating junction temp: -40°C<Tj<125°C
- Thermal Shut Down
- Post Package trimmed rising edge dead-time
- I2C Programmable Power Good Output
- Small Size 5mmx7mm PQFN
- Pb-Free (RoHS Compliant)
- External resistor allows setting up to 16 PMBus addresses

## DESCRIPTION

This family of OPTIMOS IPOL devices offers easy-to-use, fully integrated and highly efficient DC/DC regulators with PVID and I2C interface. The on-chip PWM controller and co-packaged low duty cycle optimized MOSFETs make these devices a space-efficient solution, providing accurate power delivery for low output voltage and high current applications that require a parallel VID interface.

These versatile devices offer programmability of switching frequency, output voltage, and fault/warning thresholds and fault responses while operating over a wide input range. Thus, they offer flexibility as well as system level security in event of fault conditions.

The switching frequency is programmable from 150 kHz to 1.5 MHz for an optimum solution.

The on-chip sensors and ADC along with the PVID and I2C interfaces make it easy to monitor and report input voltage, output voltage, output current and temperature.

## APPLICATIONS

- Intel® VR13 and VR12.5 based systems
- Servers and High End Desktop CPU VRs for non-core applications
- Telecom and storage applications

## BASIC APPLICATION

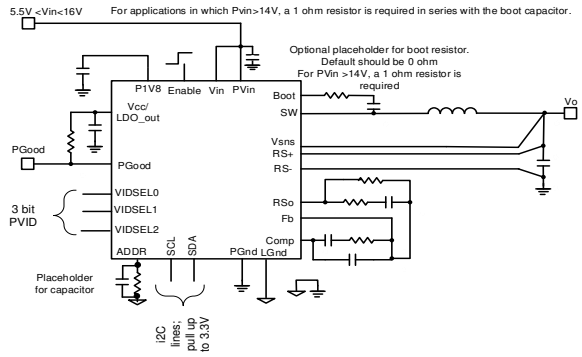



Figure 1: Typical application circuit

## PIN DIAGRAM

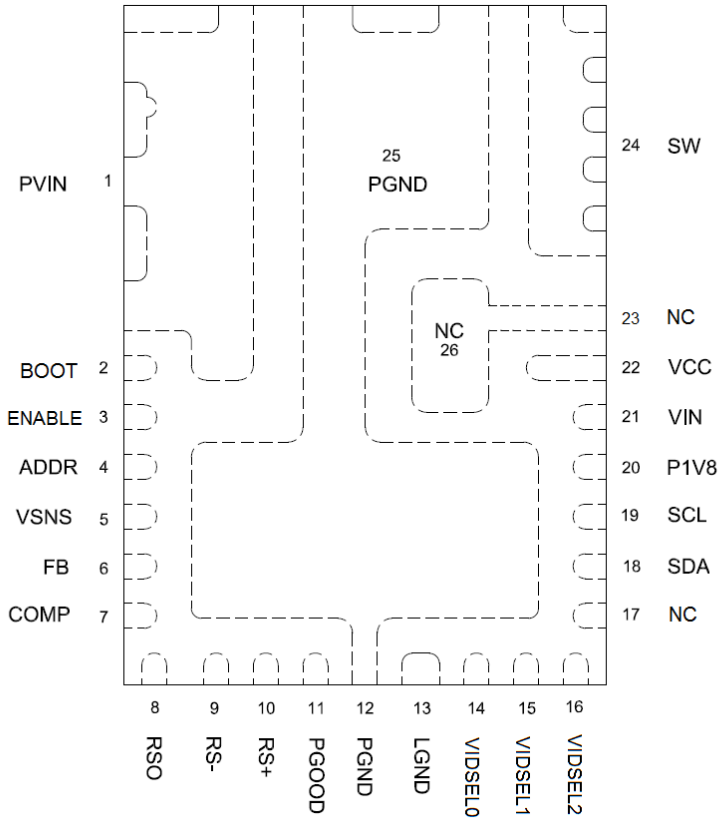



**Figure 2: IR38265 Package Top View**
**5mm X 7mm PQFN**

## ORDERING INFORMATION

| Package | Tape and Reel Qty | Part Number | Description |
|---|---|---|---|
| PQFN | 4000 | IR38265MTRPbF | 30A Buck Regulator with PVID and I2C for PVNN |

## FUNCTIONAL BLOCK DIAGRAM

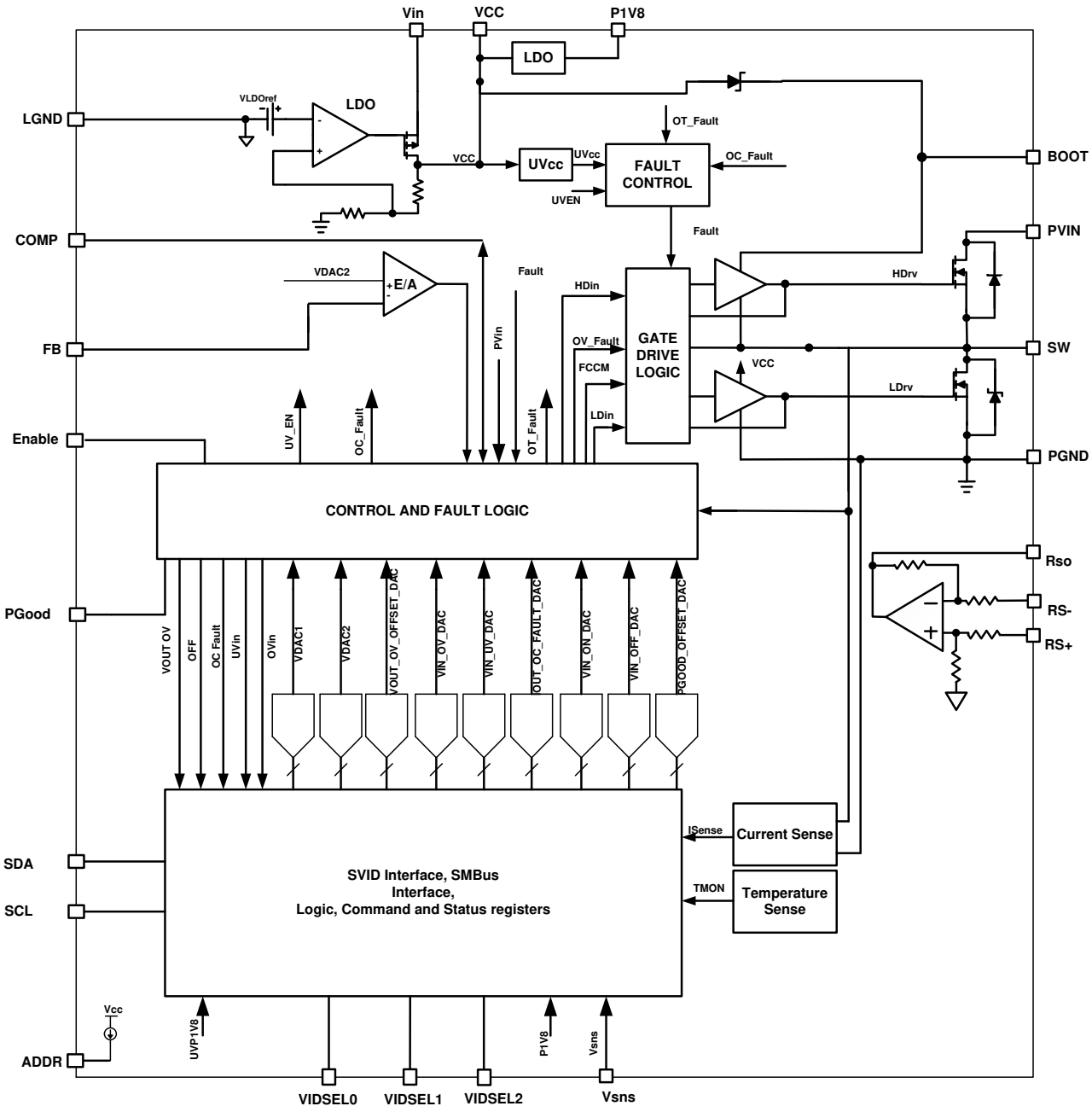



Figure 3: Simplified Block Diagram for IR38265

## PIN DESCRIPTIONS

| PIN # | PIN NAME | PIN DESCRIPTION |
|---|---|---|
| 1 | PVIN | Input voltage for power stage. Bypass capacitors between PVin and PGND should be connected very close to this pin and PGND. Typical applications use four 22 uF input capacitors and a low ESR, low ESL 0.1uF decoupling capacitor in a 0603/0402 case size. A 3.3nF capacitor may also be used in parallel with these input capacitors to reduce ringing on the Sw node. |
| 2 | Boot | Supply voltage for high side driver. A 0.1uF capacitor should be connected from this pin to the Sw pin. It is recommended to provide a placement for a 0 ohm resistor in series with the capacitor. For applications in which PVin>14V, a 1 ohm resistor is required in series with boot capacitor. |
| 3 | ENABLE | Enable pin to turn on and off the IC. |
| 4 | ADDR | A resistor should be connected from this pin to LGnd to set the I2C address offset for the device. It is recommended to provide a placement for a 10 nF capacitor in parallel with the offset resistor. |
| 5 | Vsns | Sense pin for OVP and PGood. Typically connected to a local Vout capacitor at the output of the inductor. |
| 6 | FB | Inverting input to the error amplifier. This pin is connected directly to the output of the regulator or to the output of the remote sense amplifier, via resistor divider to set the output voltage and provide feedback to the error amplifier. |
| 7 | COMP | Output of error amplifier. An external resistor and capacitor network is typically connected from this pin to FB to provide loop compensation. |
| 8 | RSo | Remote Sense Amplifier Output. When the remote sense amplifier is used, this is connected to the feedback compensation network. |
| 9 | RS- | Remote Sense Amplifier input. Connect to ground at the load. |
| 10 | RS+ | Remote Sense Amplifier input. Connect to output at the load. |
| 11 | PGood | Power Good status pin. Output is open drain. Connect a pull up resistor from this pin to VCC. If the power good voltage before VCC UVLO needs to be limited to < 500 mV, use a 49.9K pullup, otherwise a 4.99K pullup will suffice. |
| 12,25 | PGND | Power ground. This pin should be connected to the system's power ground plane. Bypass capacitors between PVin and PGND should be connected very close to PVIN pin (pin 1) and this pin. |
| 13 | LGND | Signal ground for internal reference and control circuitry. This should be connected to the PGnd plane at a quiet location using a single point connection. |
| 14 | VIDSEL0 | Used to select VID voltage registers. This is the LSB of the 3 bit PVID code that is internally decoded to select the register containing the target voltage. Only connect to Vcc via a 4.99KΩ resistor and do not use a direct connection. Do not exceed 6V. |
| 15 | VIDSEL1 | Used to select VID voltage registers. Only connect to Vcc via a 4.99KΩ resistor and do not use a direct connection. Do not exceed 6V. |
| 16 | VIDSEL2 | Used to select VID voltage registers. This is the MSB of the 3 bit PVID code that is internally decoded to select the register containing the target voltage. Only connect to Vcc via a 4.99KΩ resistor and do not use a direct connection. Do not exceed 6V. |
| 17 | NC | NC |
| 18 | SDA | I2C data serial input/output line. This should be pulled up to 3.3V-5V with a 1K-5K resistor |

| PIN # | PIN NAME | PIN DESCRIPTION |
|---|---|---|
| 19 | SCL | I2C clock line. This should be pulled up to 3.3V-5V with a 1K-5K resistor |
| 20 | P1V8 | This is the supply for the digital circuits; bypass with a 10uF capacitor to PGnd. A 2.2uF capacitor is valid however a 10uF capacitor is recommended. |
| 21 | Vin | Input Voltage for LDO. A 1 uF capacitor is placed from this pin to PGnd. If the internal bias LDO is used, tie this pin to PVin. If an external bias voltage (typically 5V) is available for Vcc, tie the Vin pin to Vcc. |
| 22 | VCC | Bias Voltage for IC and driver section, output of LDO. Add 10 uF bypass cap from this pin to PGnd. |
| 23,26 | NC | NC |
| 24 | SW | Switch node. This pin is connected to the output inductor. |

## ABSOLUTE MAXIMUM RATINGS

Stresses beyond these listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied.

| | |
|---|---|
| PVin, Vin | -0.3V to 25V |
| VCC | -0.3V to 6V |
| P1V8 | -0.3V to 2 V |
| SW | -0.3V to 25V (DC), -4V to 25V (AC, 100ns) |
| BOOT | -0.3V to 31V |
| BOOT to SW | -0.3V to 6V (DC) (Note 1), -0.3V to 6.5V (AC, 100ns) |
| PGD, other Input/output pins | -0.3V to 6V (Note 1) |
| PGND to GND, RS- to GND | -0.3V to + 0.3V |
| | |
| **THERMAL INFORMATION** | |
| Junction to ambient thermal resistance $\theta_{JA}$ | 11.1 C/W (Note 2) |
| Junction to board thermal resistance $\theta_{JB}$ | 4.16 C/W (Note 3) |
| Junction to case top thermal resistance $\theta_{JC(top)}$ | 18.9 C/W (Note 4) |
| Junction to case top thermal parameter $\Psi_{JT\ (top)}$ | 0.32 C/W (Note 2) |
| Storage Temperature Range | -55°C to 150°C |
| Junction Temperature Range | -40°C to 150°C |

(Voltages referenced to GND unless otherwise specified)

**Note 1:** Must not exceed 6V.
**Note 2:** Value obtained via thermal simulation under natural convention on a PVNN, IR38263 demo board. 10 layer, 7” x 5.5”x0.072” PCB with 1.5 oz copper at the top and bottom layer. Inner layers 2, 3, 8 and 9 have 1 oz copper and layers 4,5,6,7 have 2 oz copper. Ta = 25C was used for the simulation.
**Note 3:** PCB from note 2 and package is considered in thermal simulation with Ta=25 $^{0}$C. Pin 12 is considered.
**Note 4:** Only package is considered. Simulation is used with a cold plate that fixes top of package at Ta=25 $^{0}$C.

# ELECTRICAL SPECIFICATIONS

## RECOMMENDED OPERATING CONDITIONS

| SYMBOL | DEFINITION | MIN | MAX | UNITS |
|---|---|---|---|---|
| PVin | Input Bus Voltage | 1.5 | 16* | V |
| Vin | LDO supply voltage | 5.3 | 16 | |
| VCC | LDO output/Bias supply voltage | 4.5 | 5.5 | |
| Boot to SW | High Side driver gate voltage | 4.5 | 5.5 | |
| VO | Output Voltage | 0.5 | $0.875*PV_{in}$ | |
| $I_O$ | Output Current | 0 | 30 | A |
| Fs | Switching Frequency | 150 | 1500 | kHz |
| $T_J$ | Junction Temperature | -40 | 125 | °C |

* SW Node must not exceed 25V

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|
| **MOSFET $R_{ds(on)}$** | | | | | | |
| Top Switch | Rds(on)_Top | $V_{Boot} – V_{SW}$ = 5V, $I_D$ = 30A, Tj = 25°C | | 2.2 | | mΩ |
| Bottom Switch | Rds(on)_Bot | Vcc =5V, $I_D$ = 30A, Tj = 25°C | | 0.78 | | |
| **Reference Voltage** | | | | | | |
| Accuracy $0^0C<Tj<85^0C$ | | 1.25V<$V_{FB}$<2.555V VOUT_SCALE_LOOP=1; | -1 | | +1 | % |
| | | 0.75V<$V_{FB}$<1.25V VOUT_SCALE_LOOP=1; | -0.75 | | +0.75 | |
| | | 0.45V<$V_{FB}$<0.75V VOUT_SCALE_LOOP=1; | -0.5 | | +0.5 | % |
| Accuracy $-40^0C<Tj<125^0C$ | | 1.25V<$V_{FB}$<2.555V VOUT_SCALE_LOOP=1; | -1.6 | | +1.6 | % |
| | | 0.75V<$V_{FB}$<1.25V VOUT_SCALE_LOOP=1; | -1.0 | | +1.0 | % |
| | | 0.45V<$V_{FB}$<0.75V VOUT_SCALE_LOOP=1; | -2.0 | | +2.0 | % |
| **Supply Current** | | | | | | |
| PVin range (using external Vcc=5V) | | | | 1.5-16 | | V |
| Vin range (using internal LDO) | | Fsw=600kHz | | 5.3-16 | | V |

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|
| | | Fsw=1.5MHz | | 5.5-16 | | |
| Vin range (when Vin=Vcc) | | | 4.5 | 5.0 | 5.5 | V |
| $V_{in}$ Supply Current (Standby) (internal Vcc) | $I_{in(Standby)}$ | Enable low, No Switching, Vin=16V, low power mode enabled | | 2.7 | 4 | mA |
| $V_{in}$ Supply Current (Dyn)(internal Vcc) | $I_{in(Dyn)}$ | Enable high, Fs = 600kHz, Vin=16V | | 39 | 50 | mA |
| VCC Supply Current (Standby)(external Vcc) | $I_{cc(Standby)}$ | Enable low, No Switching, Vcc=5.5V, low power mode enabled | | 2.7 | 5 | mA |
| VCC Supply Current (Dyn)(external Vcc) | $I_{cc(Dyn)}$ | Enable high, Fs = 600kHz, Vcc=5.5V | | 39 | 50 | mA |
| **Under Voltage Lockout** | | | | | | |
| VCC – Start – Threshold | VCC_UVLO_Start | VCC Rising Trip Level | 4.0 | 4.2 | 4.4 | V |
| VCC – Stop – Threshold | VCC_UVLO_Stop | VCC Falling Trip Level | 3.7 | 3.9 | 4.1 | |
| Enable – Start – Threshold | Enable_UVLO_Start | Supply ramping up | 0.55 | 0.6 | 0.65 | V |
| Enable – Stop – Threshold | Enable_UVLO_Stop | Supply ramping down | 0.35 | 0.4 | 0.45 | |
| Enable leakage current | Ien | Enable=5.5V | | | 1 | µA |
| **Oscillator** | | | | | | |
| Ramp Amplitude | Vramp | PVin=5V, D=Dmax, Note 2 | | 0.71 | | Vp-p |
| | | PVin=12V, D=Dmax, Note 2 | | 1.84 | | |
| | | PVin=16V,D=Dmax, Note 2 | | 2.46 | | |
| Ramp Offset | Ramp (os) | Note 2 | | 0.22 | | V |
| Min Pulse Width | Dmin (ctrl) | Note 2 | | 35 | 50 | ns |
| Fixed Off Time | | Note 2 Fs=1.5MHz | | 100 | 150 | ns |
| Max Duty Cycle | Dmax | Fs=400kHz | 86 | 87.5 | 89 | % |
| **Error Amplifier** | | | | | | |
| Input Bias Current | IFb(E/A) | | -0.5 | | +0.5 | µA |
| Sink Current | Isink(E/A) | | 0.6 | 1.1 | 1.8 | mA |
| Source Current | Isource(E/A) | | 8 | 13 | 25 | mA |
| Slew Rate | SR | Note 2 | 7 | 12 | 20 | V/µs |
| Gain-Bandwidth Product | GBWP | Note 2 | 20 | 30 | 40 | MHz |
| DC Gain | Gain | Note 2 | 100 | 110 | 120 | dB |
| Maximum Voltage | Vmax(E/A) | | 2.8 | 3.9 | 4.3 | V |
| Minimum Voltage | Vmin(E/A) | | | | 100 | mV |

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|
| **Remote Sense Differential Amplifier** | | | | | | |
| Unity Gain Bandwidth | BW_RS | Note 2 | 3 | 6.4 | | MHz |
| DC Gain | Gain_RS | Note 2 | | 110 | | dB |
| Offset Voltage | Offset_RS | 0.5V<RS+<2.555V, 4kOhm load<br>$27^0C<Tj<85^0C$ | -1.6 | 0 | 1.6 | mV |
| | | 0.5V<RS+<2.555V, 4kOhm load<br>$-40^0C<Tj<125^0C$ | -3 | | 3 | |
| Source Current | Isource_RS | V_RSO=1.5V, V_RSP=4V | 11 | | 16 | mA |
| Sink Current | Isink_RS | | 0.4 | 1 | 2 | mA |
| Slew Rate | Slew_RS | Note 2, Cload = 100pF | 2 | 4 | 8 | V/µs |
| RS+ input impedance | Rin_RS+ | | 36 | 55 | 74 | Kohm |
| RS- input impedance | Rin_RS- | Note 2 | 36 | 55 | 74 | Kohm |
| Maximum Voltage | Vmax_RS | V(VCC) – V(RS+) | 0.5 | 1 | 1.5 | V |
| Minimum Voltage | Min_RS | | | 4 | 20 | mV |
| **Bootstrap Diode** | | | | | | |
| Forward Voltage | | I(Boot) = 40mA | 150 | 300 | 450 | mV |
| **Switch Node** | | | | | | |
| SW Leakage Current | Isw | SW = 0V, Enable = 0V | | | 1 | µA |
| | Isw_En | SW=0; Enable= 2V | | 18 | | |
| **Internal Regulator (VCC/LDO)** | | | | | | |
| Output Voltage | VCC | Vin(min) = 5.5V, Io=0mA, Cload = 10uF | 4.8 | 5.15 | 5.4 | V |
| | | Vin(min) = 5.5V, Io=70mA, Cload = 10uF | 4.5 | 4.99 | 5.2 | |
| VCC dropout | VCC_drop | Io=0-70mA, Cload = 10uF, Vin=5.1V | | | 0.7 | V |
| Short Circuit Current | Ishort | | | 110 | | mA |
| **Internal Regulator (P1V8)** | | | | | | |
| Output Voltage | P1V8 | Vin(min) = 4.5V, Io = 0-1mA, Cload = 2.2uF | 1.795 | 1.83 | 1.905 | V |
| 1.8V UVLO Start | P1V8_UVLO_Start | 1.8V Rising Trip Level | 1.66 | 1.72 | 1.78 | V |
| 1.8V UVLO Stop | P1V8_UVLO_Stop | 1.8V Falling Trip Level | 1.59 | 1.63 | 1.68 | V |
| **Adaptive On time Mode** | | | | | | |
| Zero-crossing comparator threshold | ZC_Vth | | -4 | -1 | 2 | mV |
| Zero-crossing comparator delay | ZC_Tdly | | | 8/Fs | | s |

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|
| **FAULTS** | | | | | | |
| **Power Good** | | | | | | |
| Power Good High Threshold Rising Delay | TPDLY | Vsns rising, Vsns > Power_Good_High | | 0 | | ms |
| Power Good Low Threshold Falling delay | VPG_low_Dly | Vsns falling, Vsns < Power_Good_Low | 150 | 175 | 200 | µs |
| PGood Voltage Low | PG (voltage) | $I_{PGood}$ = -5mA | | | 0.5 | V |
| **Over Voltage Protection (OVP)** | | | | | | |
| OVP Trip Threshold | OVP (trip) | Vsns rising, VOUT_SCALE_LOOP=1, Vout=0.5V | 0.57 | 0.605 | 0.63 | V |
| OVP comparator Hysteresis | OVP (hyst) | Vsns falling, VOUT_SCALE_LOOP=1, Vout=0.5V | 20 | 30 | 40 | mV |
| OVP Fault Prop Delay | OVP (delay) | Vsns rising, Vsns-OVP(trip)>200 mV | | 200 | | ns |
| **Over-Current Protection** | | | | | | |
| OC Trip Current | $I_{TRIP}$ | OC limit=40, VCC = 5.05V, $T_j$=25$^0$C | 36 | 40 | 44 | A |
| | | OC limit=16A, VCC = 5.05V, $T_j$=25$^0$C | 12.5 | 16 | 19.5 | A |
| OCset Current Temperature coefficient | OCSET(temp) | -40$^0$C to 125$^0$C, VCC=5.05V, Note 2 | | 5900 | | ppm/°C |
| Hiccup blanking time | Tblk_Hiccup | Note 2 | | 20 | | ms |
| **Thermal Shutdown** | | | | | | |
| Thermal Shutdown | | Note 2 | | 145 | | °C |
| Hysteresis | | Note 2 | | 25 | | °C |
| **Input Over-Voltage Protection** | | | | | | |
| PVin overvoltage threshold | $PVin_{OV}$ | | 22 | 23.7 | 25 | V |
| PVin overvoltage Hysteresis | $PVin_{ov\ hyst}$ | | | 2.4 | | V |
| **MONITORING AND REPORTING** | | | | | | |
| Bus Speed[1] | | | | 100 | 400 | kHz |
| Iout & Vout filter | | | | 78 | | Hz |
| Iout & Vout Update rate | | | | 31.25 | | kHz |
| Vin & Temperature filter | | | | 78 | | Hz |
| Vin & Temperature update rate | | | | 31.25 | | kHz |

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|
| **Output Voltage Reporting** | | | | | | |
| Resolution | $N_{Vout}$ | Note 2 | | 1/256 | | V |
| Lowest reported Vout | Vomon_low | Vsns=0V | | 0 | | V |
| Highest reported Vout | Vomon_high | VOUT_SCALE_LOOP=1, Vsns=3.3V | | 3.3 | | V |
| | | VOUT_SCALE_LOOP=0.5, Vsns=3.3V | | 6.6 | | V |
| | | VOUT_SCALE_LOOP=0.25, Vsns=3.3V | | 13.2 | | V |
| | | VOUT_SCALE_LOOP=0.125 , Vsns=3.3V | | 26.4 | | V |
| Vout reporting accuracy | | $0^0$C to $85^0$C, 4.5V<Vcc<5.5V, 1V<Vsns≤ 1.5V VOUT_SCALE_LOOP=1 | | +/- 0.6 | | % |
| | | $0^0$C to $85^0$C, 4.5V<Vcc<5.5V, Vsns> 1.5V VOUT_SCALE_LOOP=1 | | +/-1 | | |
| | | $0^0$C to $125^0$C, 4.5V<Vcc<5.5V, Vsns>0.9V VOUT_SCALE_LOOP=1 | | +/- 1.5 | | |
| | | $0^0$C to $125^0$C, 4.5V<Vcc<5.5V, 0.5V<Vsns<0.9V VOUT_SCALE_LOOP=1 | | +/-3 | | |
| **Iout Reporting** | | | | | | |
| Resolution | $N_{Iout}$ | Note 2 | | 0.0625 | | A |
| Iout (digital) monitoring Range | Iout_dig | | 0 | | 40 | A |
| Iout_dig Accuracy | I | $0^0$C to $125^0$C, 4.5V<Vcc<5.5V, 5A < Iout <30A | | +/-5 | | % |
| **Temperature Reporting** | | | | | | |
| Resolution | $N_{Tmon}$ | Note 2 | | 1 | | °C |
| Temperature Monitoring Range | Tmon_dig | | -40 | | 150 | °C |
| Thermal shutdown hysteresis | | Note 2 | | 25 | | °C |
| **Input Voltage Reporting** | | | | | | |
| Resolution | $N_{PVin}$ | Note 2 | | 1/32 | | V |
| Monitoring Range | PMBVinmon | | 0 | | 21 | V |
| Monitoring accuracy | | $0^0$C to $85^0$C, 4.5V<Vcc<5.5V, | -1.5 | | 1.5 | |

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|
| | | PVin>10V | | | | % |
| | | -40$^0$C to 125$^0$C, 4.5V<Vcc<5.5V, PVin>14V | -1.5 | | 1.5 | |
| | | -40$^0$C to 125$^0$C, 4.5V<Vcc<5.5V, 7V<PVin<14V | -4 | | 4 | |
| **I2C Interface Timing Specifications** | | | | | | |
| I2C Operating frequency | $F_{SMB}$ | | | | 400 | kHz |
| Bus Free time between Start and Stop condition | $T_{BUF}$ | | 1.3 | | | µs |
| Hold time after (Repeated) Start Condition. After this period, the first clock is generated. | $T_{HD:STA}$ | | 0.6 | | | µs |
| Repeated start condition setup time | $T_{SU:STA}$ | | 0.6 | | | µs |
| Stop condition setup time | $T_{SU:STO}$ | | 0.6 | | | µs |
| Data Rising Threshold | | | 1.339 | | 1.766 | V |
| Data Falling Threshold | | | 1.048 | | 1.495 | V |
| Clock Rising Threshold | | | 1.339 | | 1.766 | V |
| Clock Falling Threshold | | | 1.048 | | 1.499 | V |
| Data Rising Threshold LVT | | | 0.7 | | 0.9 | V |
| Data Falling Threshold LVT | | | 0.45 | | 0.65 | V |
| Clock Rising Threshold LVT | | | 0.7 | | 0.9 | V |
| Clock Falling Threshold LVT | | | 0.45 | | 0.65 | V |
| Data Hold Time | $T_{HD:DAT}$ | | 300 | | 900 | ns |
| Data Setup Time | $T_{SU:DAT}$ | | 100 | | | ns |
| Data pulldown resistance | | | 8 | 11 | 16 | Ω |
| Clock low time out | $T_{TIMEOUT}$ | | 25 | | 35 | ms |
| Clock low period | $T_{LOW}$ | | 1.3 | | | µs |
| Clock High Period | $T_{HIGH}$ | | 0.6 | | 50 | µs |
| **Digital Inputs – Low Vth Type 2 (VIDSELx)** | | | | | | |
| Input High Voltage | | | 0.65 | - | - | V |

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|
| Input Low Voltage | | | - | - | 0.45 | V |
| Hysteresis | | | - | 95 | - | mV |
| Input Leakage Current | | Vpad = 0 to 2V | - | - | ±1 | µA |

**Notes**

2. Guaranteed by design but not tested in production
3. Guaranteed by statistical correlation, but not tested in production

# TYPICAL APPLICATION DIAGRAMS

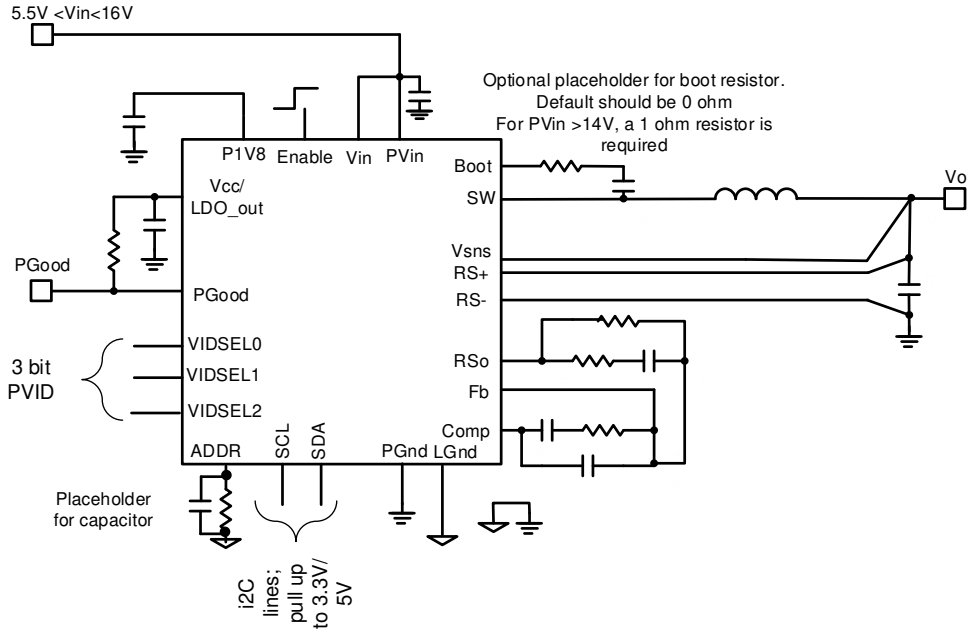



**Figure 4: Using the internal LDO, Vo < 2.555V**

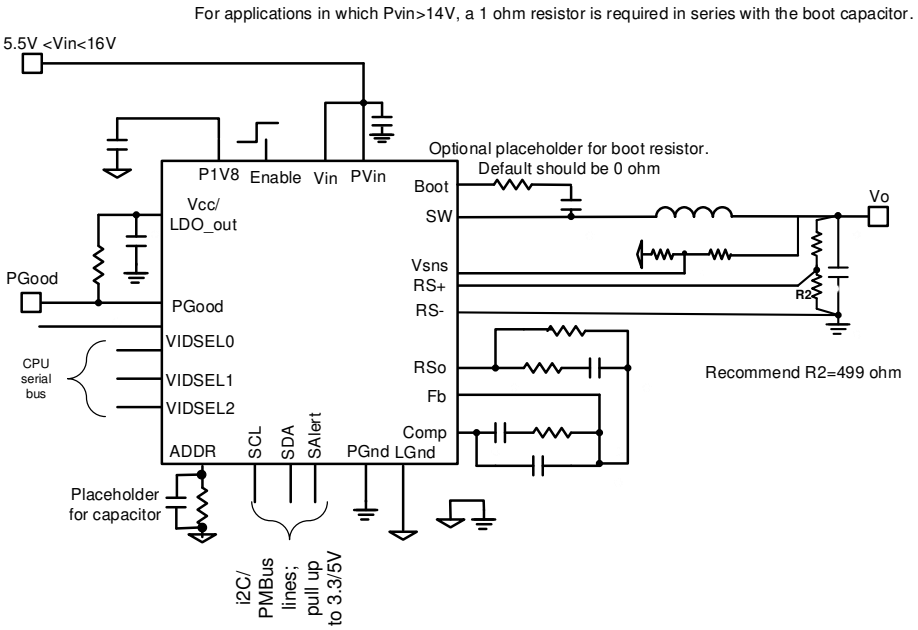



**Figure 5: Using the internal LDO, Vo > 2.555V**

# TYPICAL APPLICATION DIAGRAMS

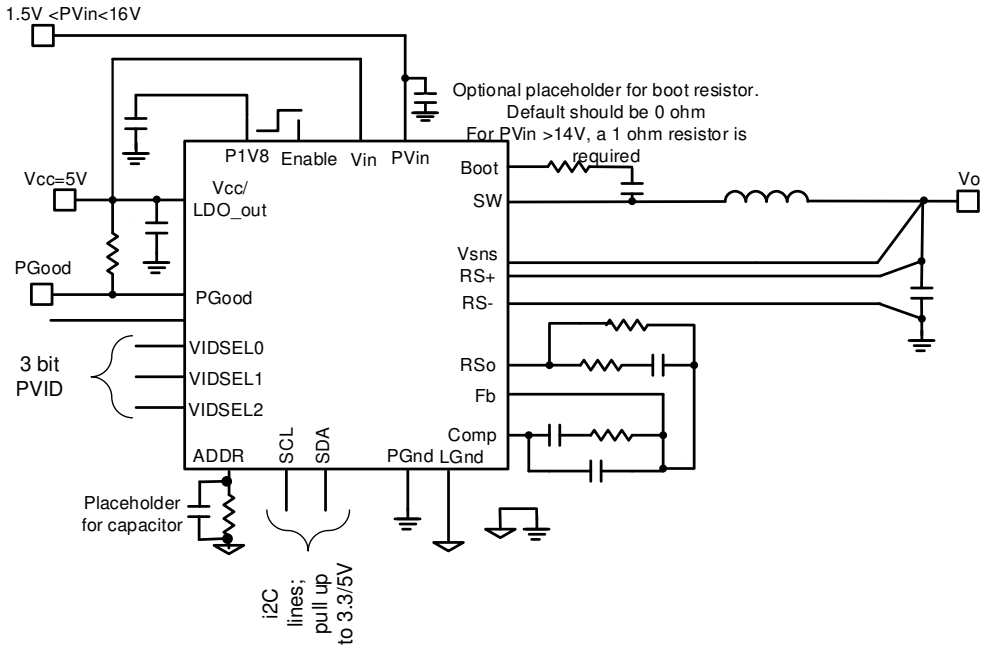



Figure 6: Using external Vcc, Vo<2.555V

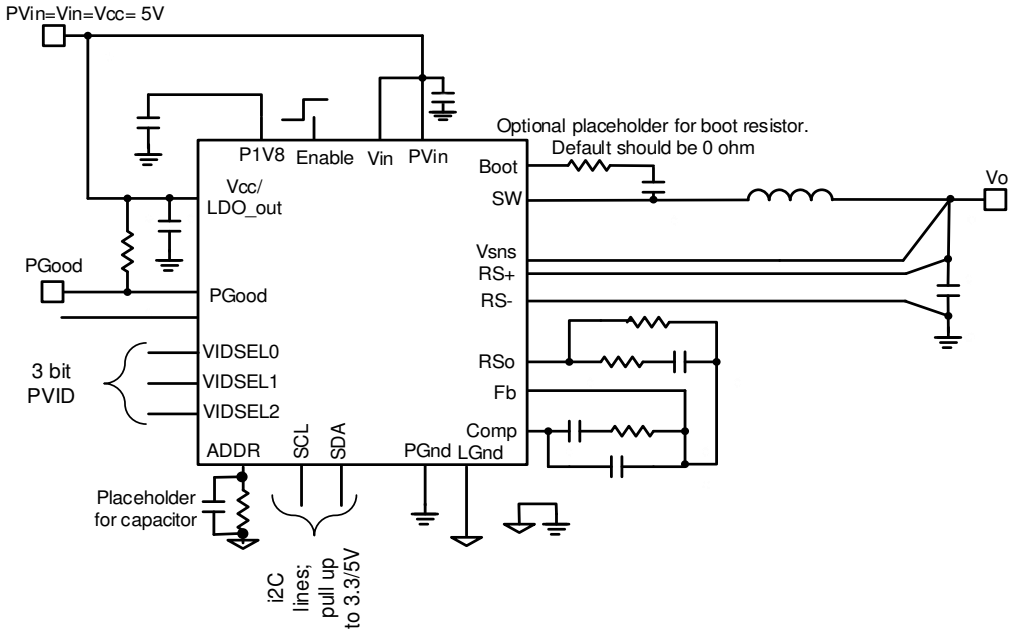
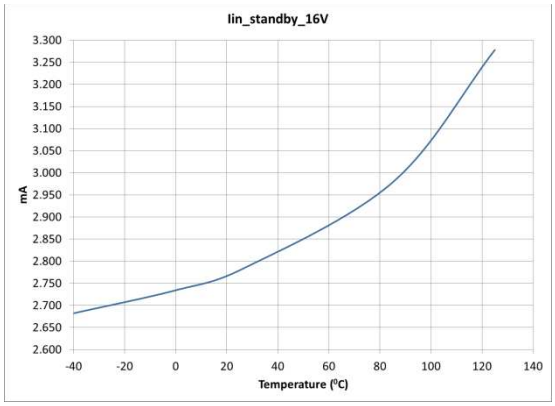
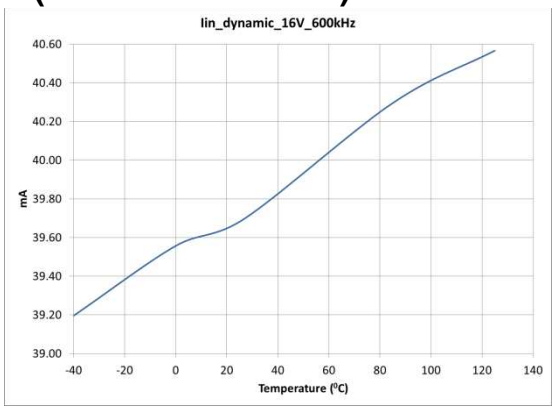
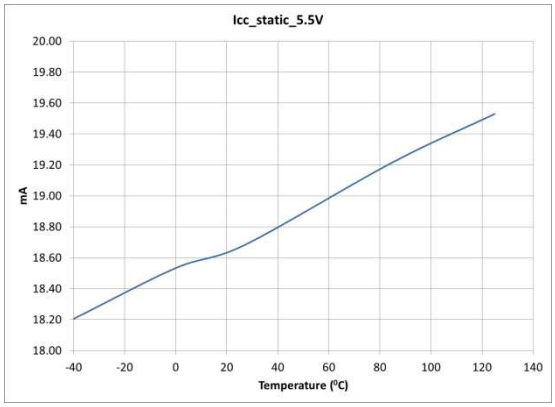


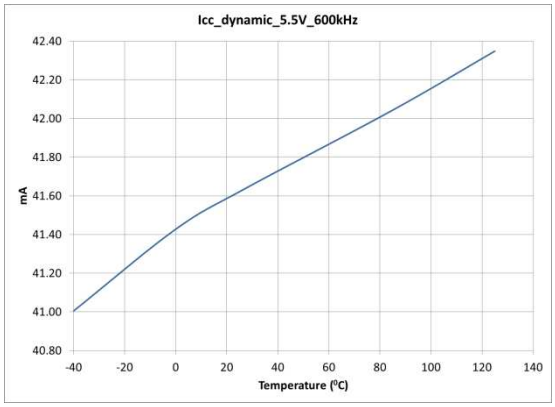

Figure 7: Single 5V application, Vo<2.555V

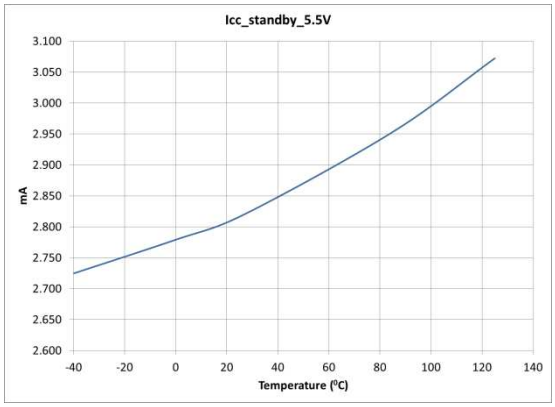
## TYPICAL OPERATING CHARACTERISTICS (-40°C TO +125°C)

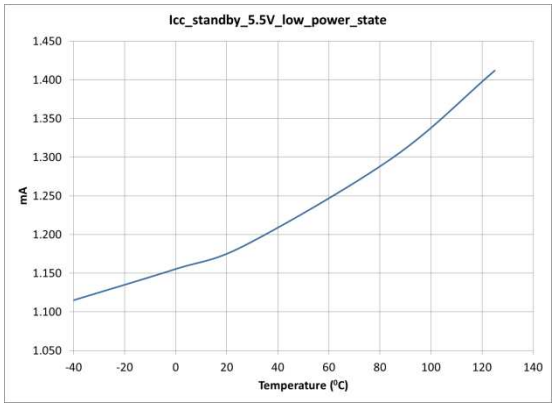


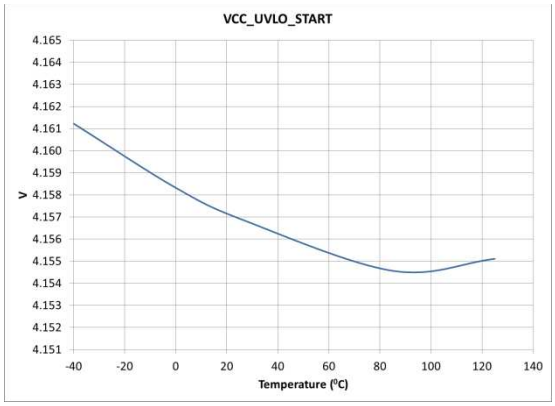



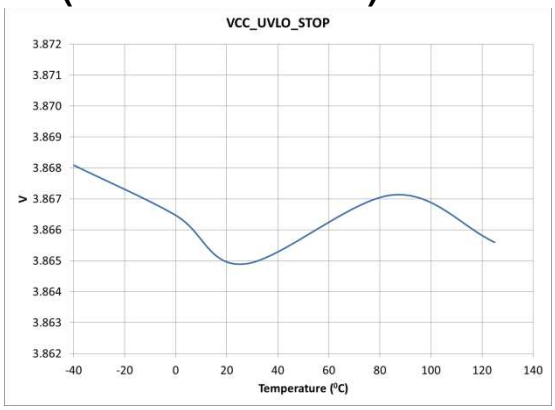



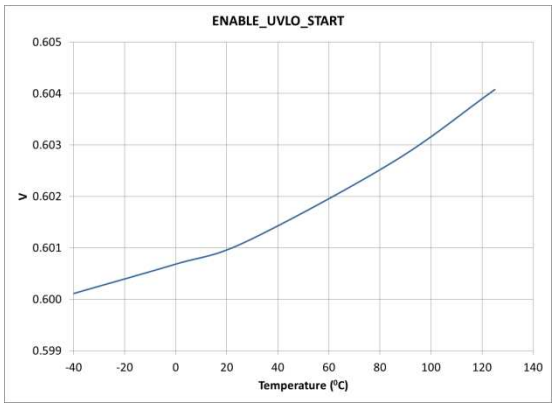



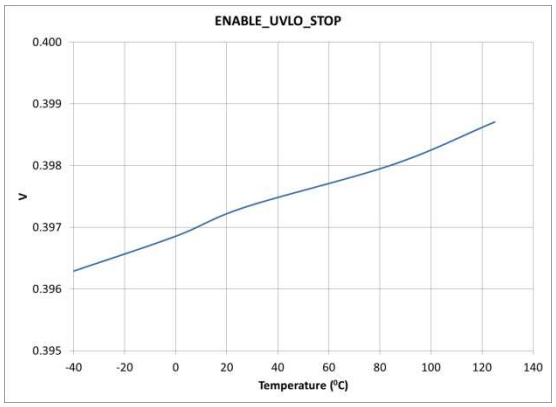



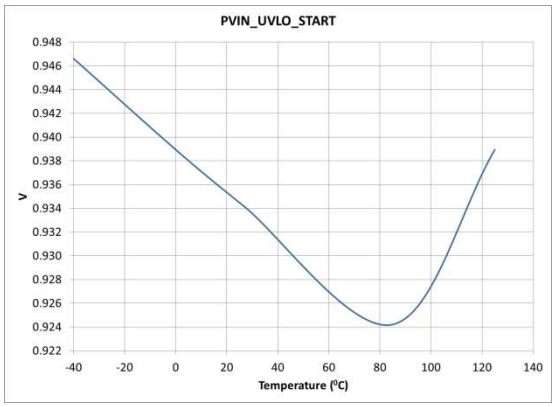
## TYPICAL OPERATING CHARACTERISTICS (-40°C TO +125°C)

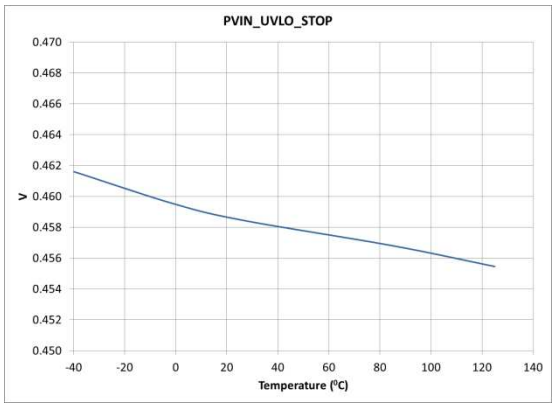


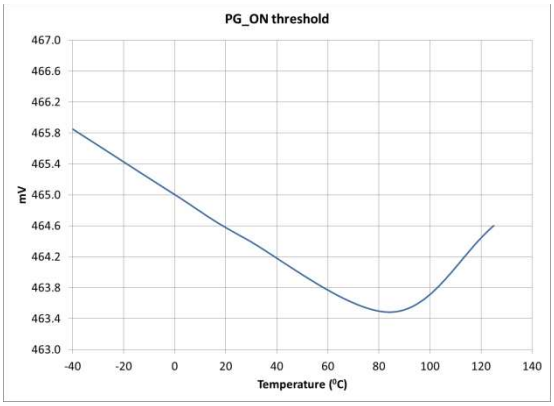



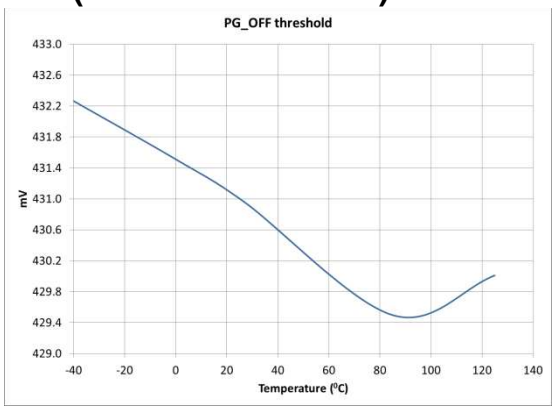



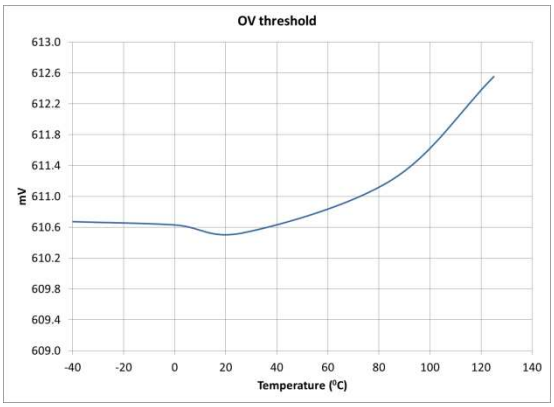



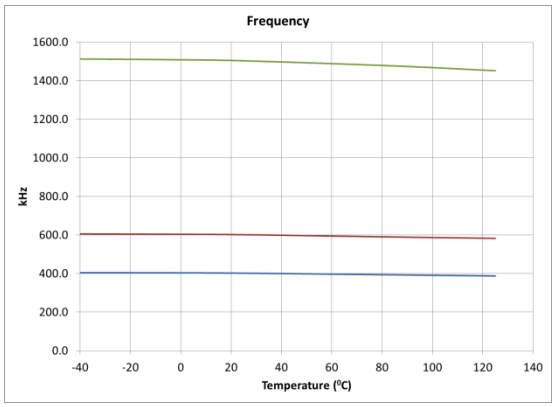



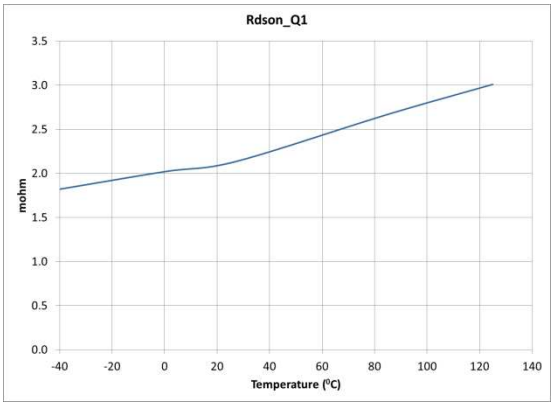
## TYPICAL OPERATING CHARACTERISTICS (-40°C TO +125°C)

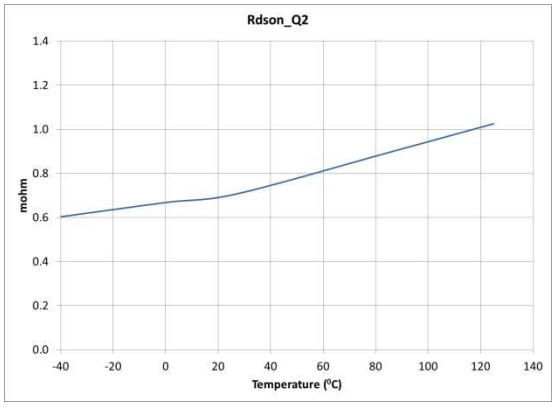


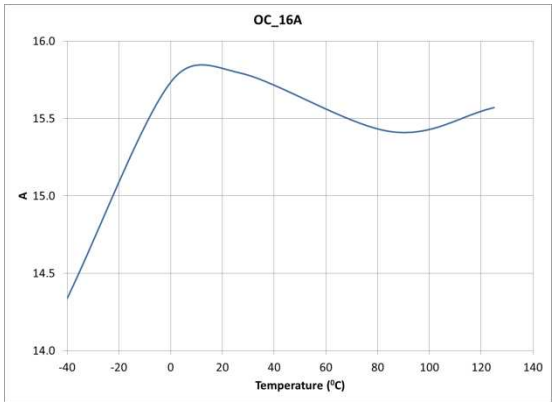



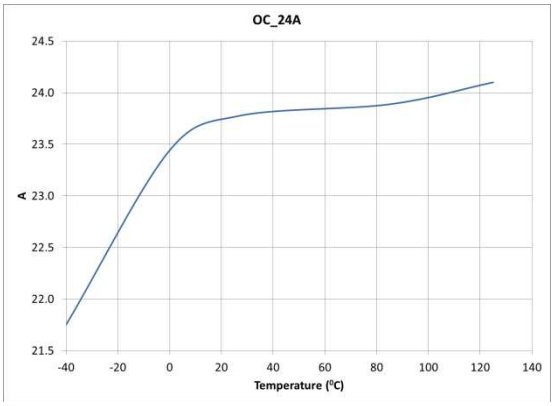



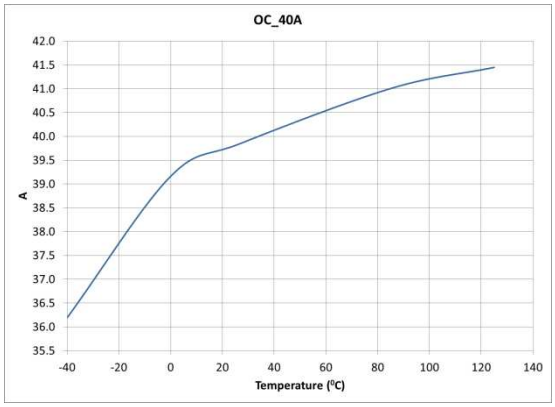



## TYPICAL OPERATING CHARACTERISTICS (-40°C TO +125°C)



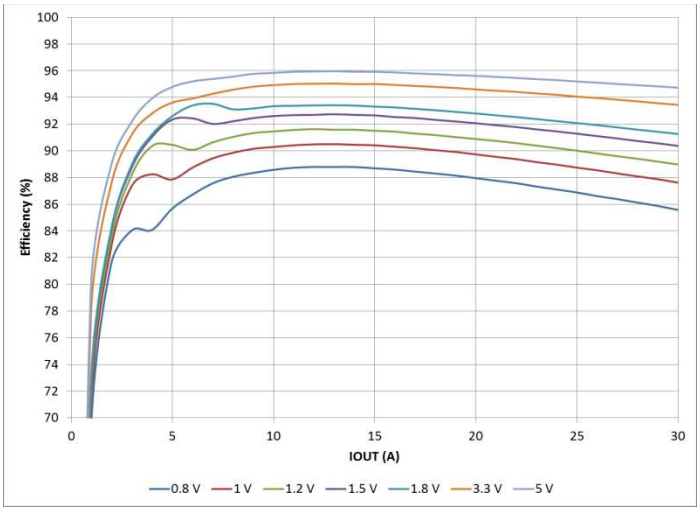



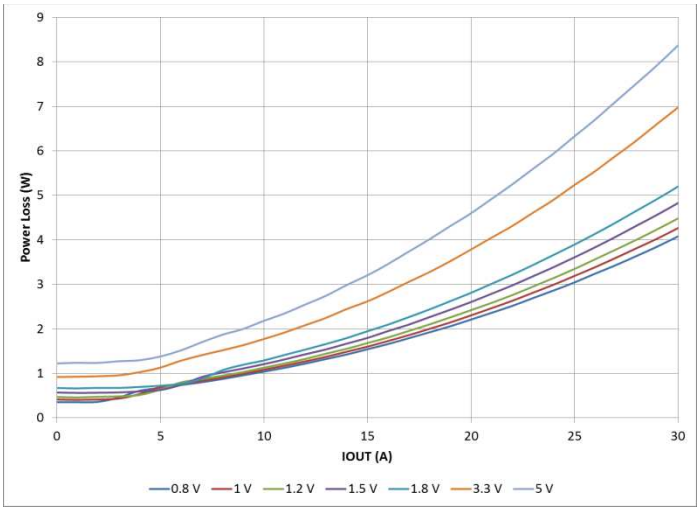



# TYPICAL EFFICIENCY AND POWER LOSS CURVES

PVin = Vin = 12V, VCC = 5V, Io=0-30A, Fs= 600kHz, Room Temperature, No Air Flow. Note that the losses of the inductor, input and output capacitors are also considered in the efficiency and power loss curves. The table below shows the indicator used for each of the output voltages in the efficiency measurement.

| VOUT (V) | LOUT (uH) | P/N | DCR (mΩ) |
|---|---|---|---|
| 0.8 | 0.15 | HCB178380D-151 (Delta) | 0.15 |
| 1 | 0.15 | HCB138380D-151 (Delta) | 0.15 |
| 1.2 | 0.15 | HCB138380D-151 (Delta) | 0.15 |
| 1.5 | 0.15 | HCB138380D-151 (Delta) | 0.15 |
| 1.8 | 0.15 | HCB138380D-101 (Delta) | 0.15 |
| 3.3 | 0.32 | FP1308R3-R32-R (Cooper) | 0.32 |
| 5 | 0.32 | FP1308R3-R32-R (Cooper) | 0.32 |

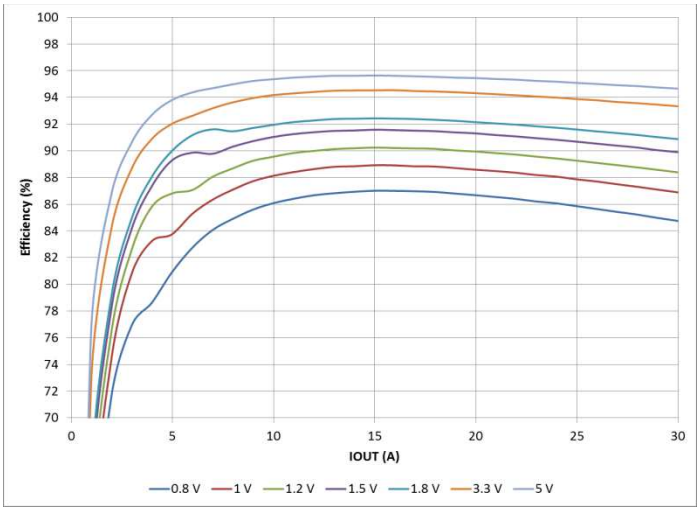


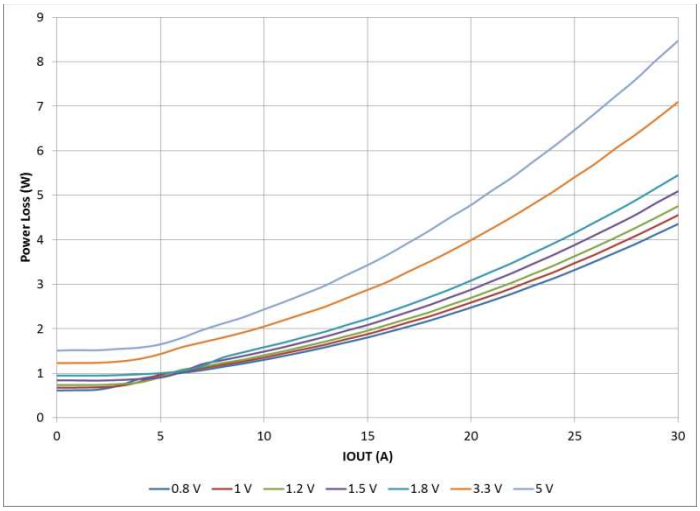



# TYPICAL EFFICIENCY AND POWER LOSS CURVES

PVin = Vin = 12V, Internal LDO, Io=0-30A, Fs= 600kHz, Room Temperature, No Air Flow. Note that the losses of the inductor, input and output capacitors are also considered in the efficiency and power loss curves. The table below shows the indicator used for each of the output voltages in the efficiency measurement.

| VOUT (V) | LOUT (uH) | P/N | DCR (mΩ) |
|---|---|---|---|
| 0.8 | 0.15 | HCB178380D-151 (Delta) | 0.15 |
| 1 | 0.15 | HCB138380D-151 (Delta) | 0.15 |
| 1.2 | 0.15 | HCB138380D-151 (Delta) | 0.15 |
| 1.5 | 0.15 | HCB138380D-151 (Delta) | 0.15 |
| 1.8 | 0.15 | HCB138380D-101 (Delta) | 0.15 |
| 3.3 | 0.32 | FP1308R3-R32-R (Cooper) | 0.32 |
| 5 | 0.32 | FP1308R3-R32-R (Cooper) | 0.32 |

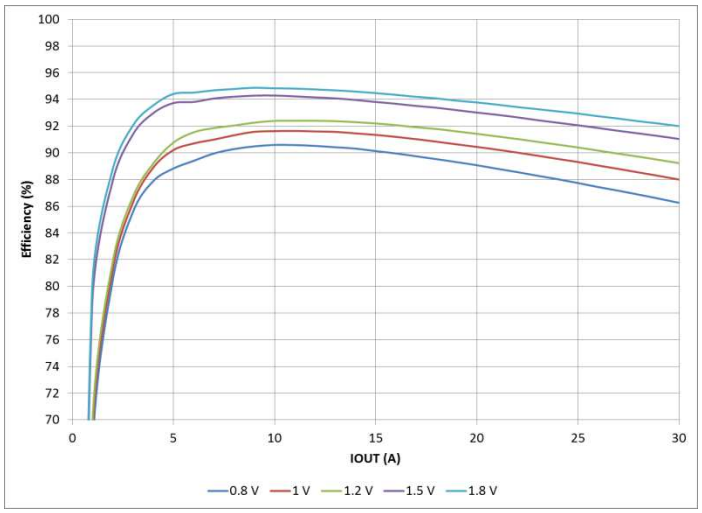


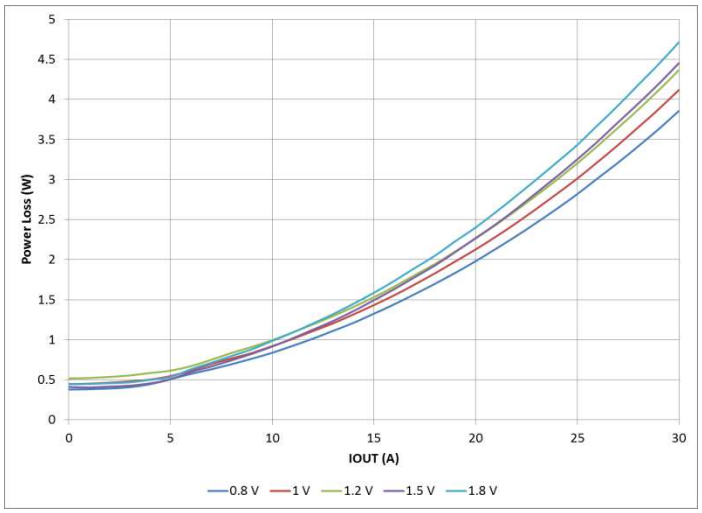



# TYPICAL EFFICIENCY AND POWER LOSS CURVES

PVin = Vin = VCC = 5V, Io=0-30A, Fs= 600kHz, Room Temperature, No Air Flow. Note that the losses of the inductor, input and output capacitors are also considered in the efficiency and power loss curves. The table below shows the indicator used for each of the output voltages in the efficiency measurement.

| VOUT (V) | LOUT (uH) | P/N | DCR (mΩ) |
|---|---|---|---|
| 0.8 | 0.1 | HCB138380D-101 (Delta) | 0.15 |
| 1 | 0.1 | HCB138380D-101 (Delta) | 0.15 |
| 1.2 | 0.15 | HCB138380D-101 (Delta) | 0.15 |
| 1.5 | 0.15 | HCB138380D-151 (Delta) | 0.15 |
| 1.8 | 0.15 | HCB138380D-151 (Delta) | 0.15 |



# THEORY OF OPERATION

## DESCRIPTION

The IR38265 is a 30A rated synchronous buck converter that supports II2C communication. This device also has 3 pins that function as a parallel VID interface that can be used to set the output voltage to one of eight pre-programmed settings. They use an externally compensated fast, analog, PWM voltage mode control scheme to provide good noise immunity as well as fast dynamic response in a wide variety of applications. At the same time, the digital communication interfaces allow complete configurability of output setting and fault functions, as well as telemetry.

The switching frequency is programmable from 150 kHz to 1500 kHz and provides the capability of optimizing the design in terms of size and performance. Recommend 500 kHz or higher frequencies.

This device provides precisely regulated output voltages from 0.5V to 0.875*PVin programmed via two external resistors or through the communication interfaces. They operate with an internal bias supply (LDO), typically 5.2V. This allows operation with a single supply. The output of this LDO is brought out at the Vcc pin and must be bypassed to the system power ground with a 10 uF decoupling capacitor. The Vcc pin may also be connected to the Vin pin, and an external Vcc supply between 4.5V and 5.5V may be used, allowing an extended operating bus voltage (PVin) range from 1.5V to 16V.

The device utilizes the on-resistance of the low side MOSFET (synchronous MOSFET) as current sense element. This method enhances the converter's efficiency and reduces cost by eliminating the need for external current sense resistor.

The IR38265 includes two low $R_{ds(on)}$ MOSFETs using Infineon's OptiMOS technology. These are specifically designed for low duty cycle, high efficiency applications.

## DEVICE POWER-UP AND INITIALIZATION

During the power-up sequence, when Vin is brought up, the internal LDO converts it to a regulated 5.2V at Vcc. There is another LDO which further converts this down to 1.8V to supply the internal digital circuitry. An under-voltage lockout circuit monitors the voltage of VCC pin and the P1V8 pin, and holds the Power-on-reset (POR) low until these voltages exceed their thresholds and the internal 48 MHz oscillator is stable. When the device comes out of reset, it initializes a multiple times programmable (MTP) memory load cycle, where the contents of the MTP are loaded into the working registers. Once the registers are loaded from MTP, the designer can use the I2C interface to re-configure the various parameters to suit the specific VR design requirements if desired, irrespective of the status of Enable.

The typical default configuration utilizes the internal LDO to supply the VCC rail when PVin is brought up. For this configuration power conversion is enabled only when the Enable pin voltage exceeds its under-voltage threshold, the PVin bus voltage exceeds its under-voltage threshold, the contents of the MTP have been fully loaded into the working registers and the device address has been read. The initialization sequence is shown in Figure 8. Another common default configuration uses an external power supply for the VCC rail. While in this configuration it is recommended to ensure the VCC rail reaches its target voltage prior the enable signal goes high.

Additional options are available to enable the device power conversion through software and these options may be configured to override the default by using the I2C interface.

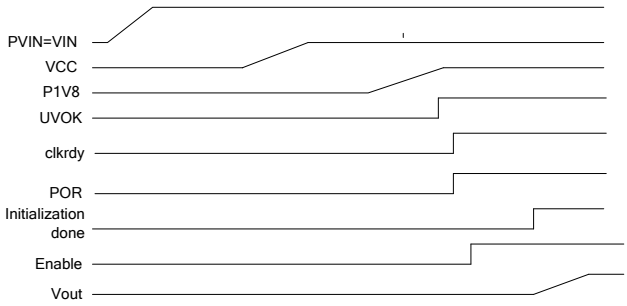



**Figure 8: Initialization sequence showing PVin, Vin, Vcc, 1.8V, Enable and Vout signals as well as the internal logic signals**

## I2C COMMUNICATION

The IR38265 has two 7-bit registers that are used to set the base I2C address, as shown below in Table 1.

**Table 1: Registers used to set device base address**

| Register | Description |
|---|---|
| **I2C_address[6:0]** | The chip I2C address. An address of 0 will disable I2C communication. |

In addition, a resistor may be connected between the ADDR and LGND pins to set an offset from the default preconfigured I2C address (0x10) in the MTP. Up to 16 different offsets can be set, allowing 16 devices with unique addresses in a single system. This offset, and hence, the device address, is read by the internal 10 bit ADC during the initialization sequence.

Table 2 below provides the resistor values needed to set the 16 offsets from the base address.

**Table 2 : Address offset vs. External Resistor($R_{ADDR}$)**

| ADDR Resistor (Ohm) | Address Offset |
|---|---|
| **499** | +0 |
| **1050** | +1 |
| **1540** | +2 |
| **2050** | +3 |
| **2610** | +4 |
| **3240** | +5 |
| **3830** | +6 |
| **4530** | +7 |
| **5230** | +8 |

| | |
|---|---|
| **6040** | +9 |
| **6980** | +10 |
| **7870** | +11 |
| **8870** | +12 |
| **9760** | +13 |
| **10700** | +14 |
| **>11800** | +15 |

The device will then respond to I2C commands sent to this address. There is also a register bit *I2C_disable_addr_offset* that may be set in order to instruct the device to ignore the resistor offset. If this bit is set, the device will always respond to commands sent to the base address.

## MODES FOR SETTING OUTPUT VOLTAGES

The IR38265 uses the VIDSEL0, VIDSEL1 and VIDSEL2 lines to set the output voltage. The VIDSELx lines select an MTP register which holds a VID value that sets the output voltage. The MTP registers are programmable via I2C. Note that the same VID value can result in different voltages depending on which VID table, 5mV or 10mV has been selected. Table 3 shows how the VIDSELx lines are used to select the register containing the target value. It is worth noting that the VIDSEL lines may be driven with logic gates or with Open drain devices. When driven by open drain devices, a pullup resistor of 4.99K must be used. When driven by logic gates, a resistor of 4.99K is required in series with the pin. The VID tables for 5mV and 10mV VID steps are shown in the tables 4 and 5 below.

**Table 3: Mapping the VIDSEL lines to MTP registers**

| VIDSEL2 | VIDSEL1 | VIDSEL0 | Selects MTP register address |
|---|---|---|---|
| 0 | 0 | 0 | 77h |
| 0 | 0 | 1 | 78h |
| 0 | 1 | 0 | 79h |
| 0 | 1 | 1 | 7Ah |
| 1 | 0 | 0 | 7Bh |
| 1 | 0 | 1 | 7Ch |
| 1 | 1 | 0 | 7Dh |
| 1 | 1 | 1 | 7Eh |